

Title (en)

PACKING MATERIAL, PACKED BODY, MODULE ASSEMBLY, AND MODULE PACKING METHOD

Title (de)

VERPACKUNGSMATERIAL, VERPACKTER KÖRPER, MODULANORDNUNG UND MODULVERPACKUNGSVERFAHREN

Title (fr)

MATÉRIAU D'EMBALLAGE, CORPS EMBALLÉ, ENSEMBLE MODULE ET PROCÉDÉ D'EMBALLAGE DE MODULE

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Application

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Abstract (en)

The purpose of the invention is to provide a packing material capable of suppressing breakage of a header part of a module and breakage of a packaging bag packaging the module. There is provided a packing material 1 for packing modules M each having a cylindrical body part M1 and header parts M2 attached to both longitudinal ends of the body part M1 into a box B. The packing material 1 includes body part support surfaces 10 which at least partially support lower surfaces M11 of the body parts M1 of the modules M in a recumbent state, body part support walls 20 which support both side surfaces M12 of the body part M1 of each module M so as to sandwich both side surfaces M12, and top surface support walls 30 which support top surfaces M22 of both header parts M2 of the modules M. The packing material 1 is configured so that when the modules M are supported by the body part support surfaces 10, the body part support walls 20, and the top surface support walls 30, the packing material 1 is prevented from coming into contact with side surfaces M21 of the header parts M2 of the modules.

IPC 8 full level

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